Barium Titanate $BaTiO_3$

Sputtering Targets

Advanced Engineering Materials

Applications

- Ferroelectric
- Gate Dielectric
- For CMOS
- Non-volatile Memory
- Thin film capacitor

Features

- High purity
- Custom Sizes Available

Process

- Manufacturing
  - Cold pressed
  - Sintered
  - Elastomer bonded to backing plate
- Cleaning and final packaging
  - Cleaned for use in vacuum
  - Protection from environmental contaminants
  - Protection during shipment

Options

- 99.9% ex Strontium Minimum Purity
- Up to 12" Diameter Targets Available
- Planar Tiles Up to 8" X 5" for Larger Target Configurations

Specifications

Typical Analysis - 99.9% (3N) Purity

Metallic Impurities, ppm by weight

Al	As	B	Bi	Ca	Cl	Co	Cr	Cu	Fe	Hf	K	Mg
<50	<5	<10	<5	<200	<20	<50	<10	<5	<10	<15	<100	<20

Mn	N	Na	Ni	P	Pb	Pd	S	Sb	Se	Si	Sn	Sr
<300	<40	<5	<5	<5	<5	<5	<5	<5	<5	<10	<5	<5

Theoretical Density	5.999 g/cc
Typical Density	4.97 g/cc
Sputter	RF
Max Power Density (Watts/Square Inch)	20
Melting Point	1,625°C
Appearance	White/Beige/Grey
Z Ratio	0.464
Particle Size	D50

Advanced Engineering Materials

E-mail: sales@aemproduct.com
Tel: +86-731-84472418
+86-18175985920
Website: www.aemdeposition.com
Address: Rm. 408, Building 1, No. 31, Yinshan Road
Yuelu District, Changsha, Hunan 410013